SPI 2019

Chambéry, France
18-21 june 2019

23RD IEEE WORKSHOP ON SIGNAL AND POWER INTEGRITY

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Important Dates

Paper submission (2-4 pages):
March 1st, 2019

Notification of acceptance:
April 1st, 2019

CALL FOR PAPERS
23rd IEEE WORKSHOP ON SIGNAL AND POWER INTEGRITY, 18-21 JUNE 2019, CHAMBÉRY, FRANCE

Over the past two decades, the IEEE Workshop on Signal and Power Integrity (SPI) has evolved into a forum of exchange on the latest research and developments on design, characterization, modeling, simulation and testing for Signal and Power Integrity at chip, package, board and system level. The workshop brings together developers and researchers from industry and academia in order to encourage cooperation.

The Committee is looking forward to the 23rd Edition which will be hosted in the French Alps, in the beautiful city of Chambéry. The SPI 2019 technical program will include both oral and poster sessions. A number of prominent experts will be giving tutorials on areas of emerging interest. The Conference Proceedings will be published with an ISBN code and will appear in IEEE Xplore.

https://spi2019.sciencesconf.org

TOPICS

- Modeling and simulation for SI/PI
- Coupled signal and power Integrity analysis
- Noise reduction and equalization techniques
- High-speed link design and modeling
- Power distribution networks
- RF/microwave/mm-wave systems and packaging solutions
- Antennas-in-package and antennas-on-chip
- 3D IC and packages (TSV/SiP/SoC)
- Nano-interconnects and nano-structures
- Electromagnetic theory and modeling
- Transmission line theory and modeling
- Macromodeling, reduced order models
- Electromagnetic compatibility
- Design methodology/flow measurements
- Jitter and noise modeling
- Stochastic/sensitivity analysis
- Electro-thermal modeling
- Chip-package co-design
- Novel CAD concepts
- Optical interconnects